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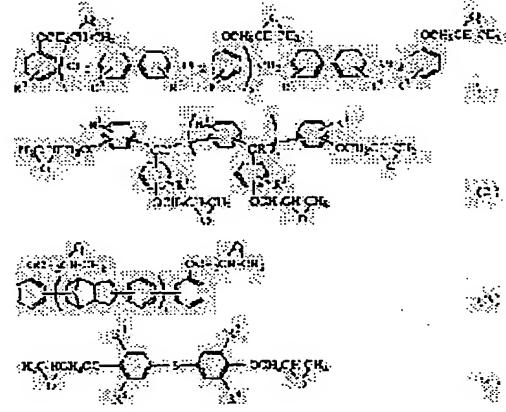
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(54) LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a liquid epoxy resin composition which has favorable adhesive properties, gives a highly moisture-proof cured product, and hence can be a sealing medium for a semiconductor device excellent in high temperature thermal shock.

SOLUTION: The liquid epoxy resin composition which comprises a liquid epoxy resin, a curing agent, a curing accelerator and an inorganic filler. The liquid epoxy resin comprises an epoxy resin (a) which has at most bifunctional epoxy groups in a molecule and is liquid at room temperature and an epoxy resin (b) which has at least bifunctional epoxy groups in a molecule as in formulae (1)–(4) and is solid at room temperature, in a weight ratio of (a)/(b)=9/1–1/4, the mixture having a viscosity of 10,000 Poise or less at 25° C, the composition having a toughness value K1c of 3.0 or more, and a semiconductor device sealed with a cured product of the composition. (In the formulae, R is a hydrogen atom, an alkyl group or a phenyl group, R1–R4 are each a hydrogen atom or a monovalent hydrocarbon group, R' is a hydrogen atom, a methyl group or an ethyl group, x is 0–10, y is 0–6, and z is an integer of 1 or more).



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